WCFS1016V1C

64K x 16 Static RAM

Features

- **3.3V operation (3.0V - 3.6V)**
- **High speed**
  - **—t_{AA} = 12 ns**
- **CMOS for optimum speed/power**
- **Data retention at 2.0V**
- **Automatic power-down when deselected**
- **Independent control of upper and lower bits**
- **Available in 44-pin TSOP II, 400-mil SOJ**

Functional Description

The WCFS1016V1C is a high-performance CMOS static RAM organized as 65,536 words by 16 bits. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

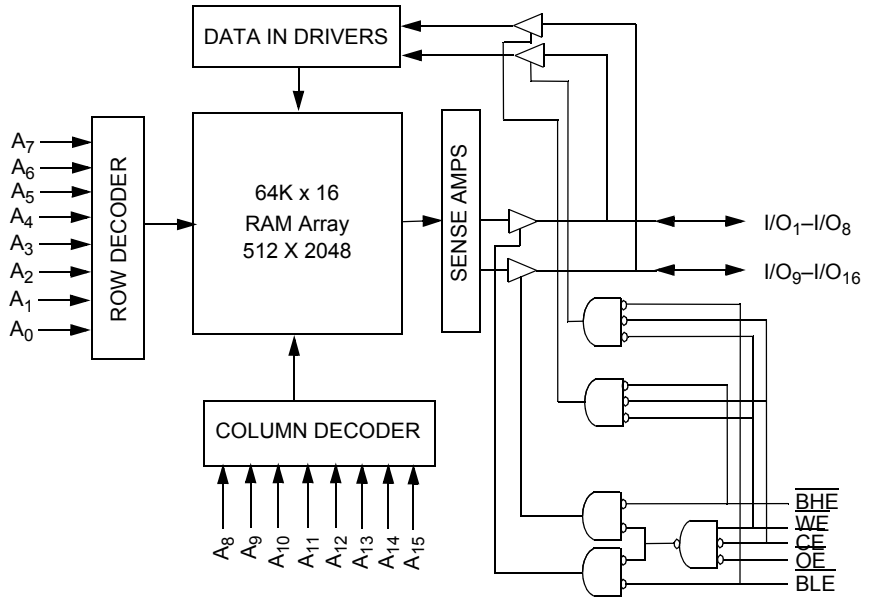
Writing to the device is accomplished by taking Chip Enable ($\overline{CE}$) and Write Enable ($\overline{WE}$) inputs LOW. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from I/O pins (I/O_1 through I/O_8), is written into the location specified on the address pins (A_0 through A_{15}). If Byte High Enable ($\overline{BHE}$) is LOW, then data from I/O pins (I/O_9 through I/O_{16}) is written into the location specified on the address pins (A_0 through A_{15}).

Reading from the device is accomplished by taking Chip Enable ($\overline{CE}$) and Output Enable ($\overline{OE}$) LOW while forcing the Write Enable ($\overline{WE}$) HIGH. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from the memory location specified by the address pins will appear on I/O_1 to I/O_8. If Byte High Enable ($\overline{BHE}$) is LOW, then data from memory will appear on I/O_9 to I/O_{16}. See the truth table at the end of this data sheet for a complete description of Read and Write modes.

The input/output pins (I/O_1 through I/O_{16}) are placed in a high-impedance state when the device is deselected ($\overline{CE}$ HIGH), the outputs are disabled ($\overline{OE}$ HIGH), the $\overline{BHE}$ and $\overline{BLE}$ are disabled ($\overline{BHE}$, $\overline{BLE}$ HIGH), or during a Write operation ($\overline{CE}$ LOW, and $\overline{WE}$ LOW).

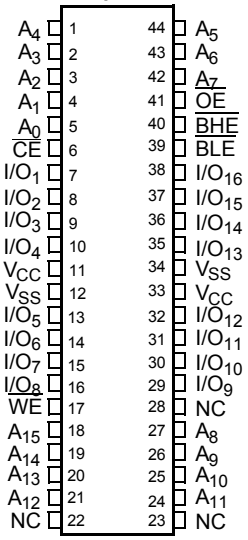
The WCFS1016V1C is available in standard 44-pin TSOP Type II 400-mil-wide SOJ packages.

Logic Block Diagram



Pin Configuration

SOJ / TSOP II
Top View



Selection Guide

	WCFS1016V1C-12	Unit
Maximum Access Time	12	ns
Maximum Operating Current	150	mA
Maximum CMOS Standby Current	5	mA

Pin Configuration

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature .....–65°C to +150°C

Ambient Temperature with Power Applied.....–55°C to +125°C

Supply Voltage on V_{CC} to Relative GND[1] .... –0.5V to +4.6V

DC Voltage Applied to Outputs in High-Z State[1] .....–0.5V to V_{CC}+0.5V

DC Input Voltage[1].....–0.5V to V_{CC}+0.5V

Current into Outputs (LOW)..... 20 mA

Static Discharge Voltage.....>2001V (per MIL-STD-883, Method 3015)

Latch-up Current.....>200 mA

Operating Range

Range	Ambient Temperature[2]	V_{CC}
Commercial	0°C to +70°C	3.3V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	WCFS1016V1C-12		Unit
			Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –4.0 mA	2.4		V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 8.0 mA		0.4	V
V_{IH}	Input HIGH Voltage		2.2	V_{CC} + 0.3	V
V_{IL}	Input LOW Voltage[1]		–0.3	0.8	V
I_{IX}	Input Load Current	GND ≤ V_I ≤ V_{CC}	–1	+1	µA
I_{OZ}	Output Leakage Current	GND ≤ V_{OUT} ≤ V_{CC}, Output Disabled	–1	+1	µA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$		150	mA
I_{SB1}	Automatic CE Power-down Current —TTL Inputs	Max. V_{CC}, $\overline{CE}$ ≥ V_{IH} V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}		40	mA
I_{SB2}	Automatic CE Power-down Current —CMOS Inputs	Max. V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3V, V_{IN} ≥ V_{CC} – 0.3V, or V_{IN} ≤ 0.3V, f = 0		5	mA

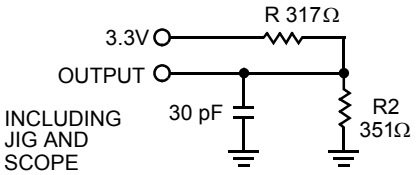
Capacitance[3]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	T_A = 25°C, f = 1 MHz, V_{CC} = 3.3V	6	pF
C_{OUT}	Output Capacitance		8	pF

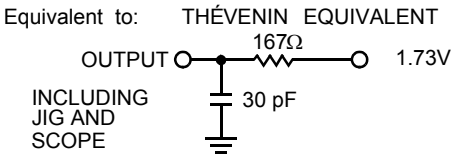
Notes:

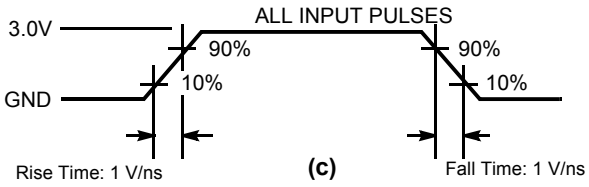
1. V_{IL} (min.) = –2.0V for pulse durations of less than 20 ns.
2. T_A is the "instant on" case temperature.
3. Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms



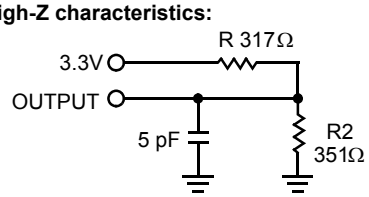
(a)





(c)

High-Z characteristics:



(b)

Switching Characteristics Over the Operating Range[4]

Parameter	Description	WCFS1016V1C-12		Unit
		Min.	Max.	
Read Cycle				
t_{RC}	Read Cycle Time	12		ns
t_{AA}	Address to Data Valid		12	ns
t_{OHA}	Data Hold from Address Change	3		ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid		12	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid		6	ns
t_{LZOE}	$\overline{OE}$ LOW to Low-Z[5]	0		ns
t_{HZOE}	$\overline{OE}$ HIGH to High-Z[5, 6]		6	ns
t_{LZCE}	$\overline{CE}$ LOW to Low-Z[5]	3		ns
t_{HZCE}	$\overline{CE}$ HIGH to High-Z[5, 6]		6	ns
t_{PU}[7]	$\overline{CE}$ LOW to Power-Up	0		ns
t_{PD}[7]	$\overline{CE}$ HIGH to Power-Down		12	ns
t_{DBE}	Byte Enable to Data Valid		6	ns
t_{LZBE}	Byte Enable to Low-Z	0		ns
t_{HZBE}	Byte Disable to High-Z		6	ns
Write Cycle[8]				
t_{WC}	Write Cycle Time	12		ns
t_{SCE}	$\overline{CE}$ LOW to Write End	9		ns
t_{AW}	Address Set-Up to Write End	8		ns
t_{HA}	Address Hold from Write End	0		ns
t_{SA}	Address Set-Up to Write Start	0		ns
t_{PWE}	$\overline{WE}$ Pulse Width	8		ns
t_{SD}	Data Set-Up to Write End	6		ns
t_{HD}	Data Hold from Write End	0		ns
t_{LZWE}	$\overline{WE}$ HIGH to Low-Z[5]	3		ns
t_{HZWE}	$\overline{WE}$ LOW to High-Z[5, 6]		6	ns
t_{BW}	Byte Enable to End of Write	8		ns

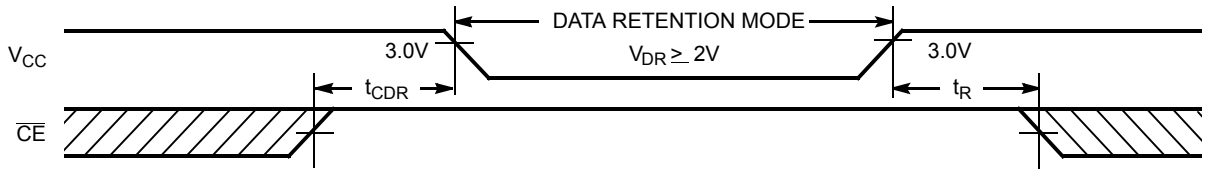
Data Retention Characteristics Over the Operating Range

Parameter	Description	Conditions[9]	Min.	Max.	Unit
V_{DR}	V_{CC} for Data Retention		2.0		V
t_{CDR}[10]	Chip Deselect to Data Retention Time	$V_{CC} = V_{DR} = 2.0V$, $\overline{CE} \geq V_{CC} - 0.3V$, $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} \leq 0.3V$	0		ns
t_R[11]	Operation Recovery Time		t_{RC}		ns

Notes:

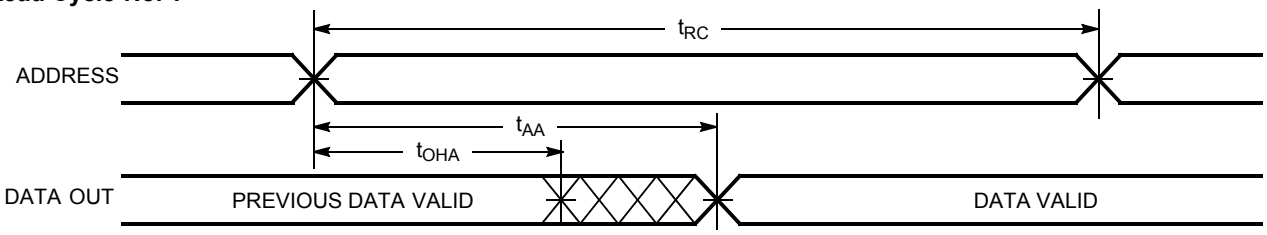
4. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
5. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
6. t_{HZOE}, t_{HZBE}, t_{HZCE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (d) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
7. This parameter is guaranteed by design and is not tested.
8. The internal Write time of the memory is defined by the overlap of $\overline{CE}$ LOW, $\overline{WE}$ LOW and $\overline{BHE}/\overline{BLE}$ LOW. $\overline{CE}$, $\overline{WE}$ and $\overline{BHE}/\overline{BLE}$ must be LOW to initiate a Write, and the transition of these signals can terminate the Write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the Write.
9. No input may exceed VCC + 0.5V.
10. Tested initially and after any design or process changes that may affect these parameters.
11. $t_r \leq 3$ ns for the –12 and –15 speeds. $t_r \leq 5$ ns for the –20 and slower speeds.

Data Retention Waveform

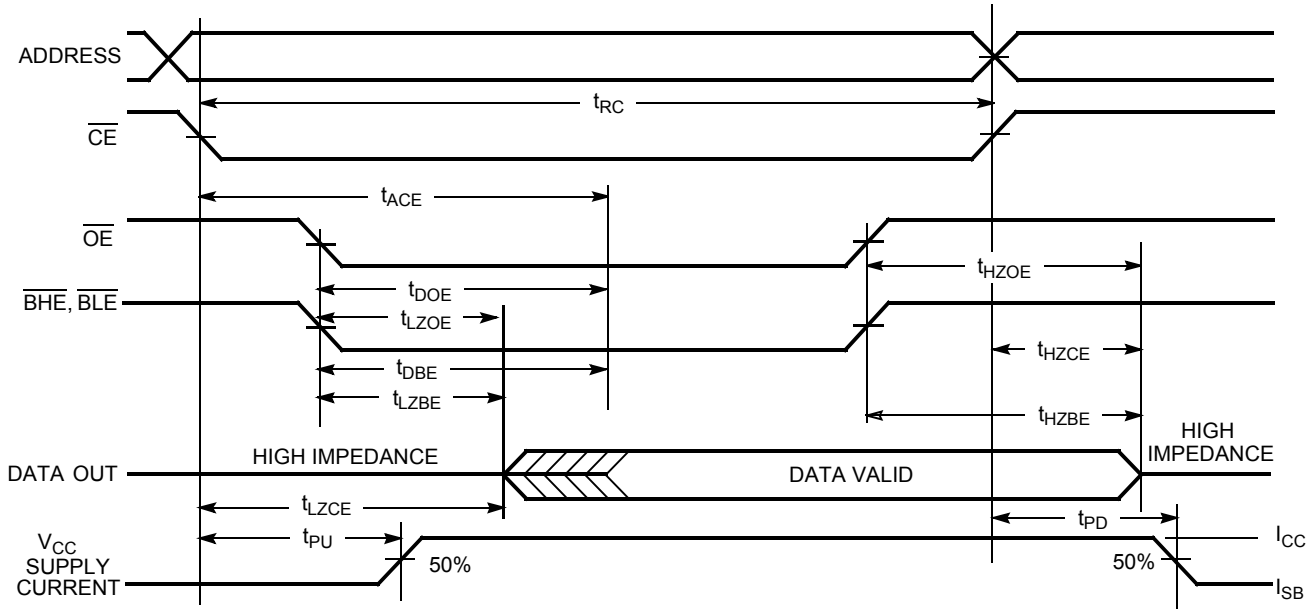


Switching Waveforms

Read Cycle No. 1[12, 13]



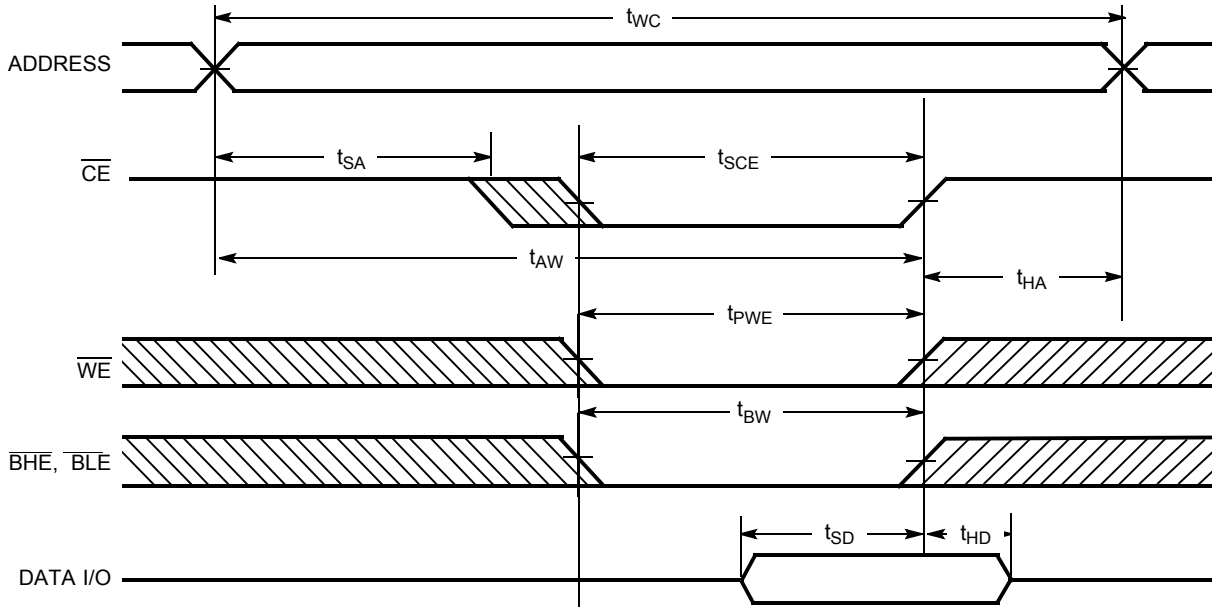
Read Cycle No. 2 ($\overline{OE}$ Controlled)[13, 14]



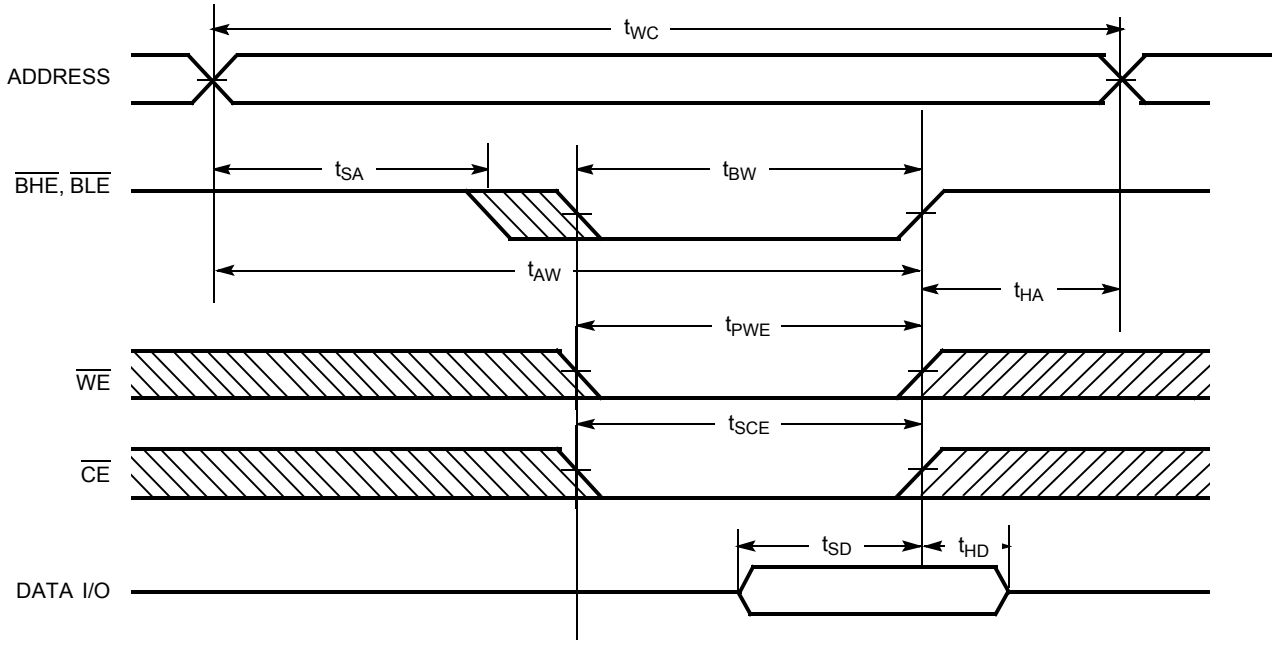
Notes:
12. Device is continuously selected. $\overline{OE}$, $\overline{CE}$, $\overline{BHE}$ and/or $\overline{BHE}$ = V_{IL}.
13. $\overline{WE}$ is HIGH for Read cycle.
14. Address valid prior to or coincident with $\overline{CE}$ transition LOW.

Switching Waveforms (continued)

Write Cycle No. 1 ($\overline{CE}$ Controlled) [15, 16]



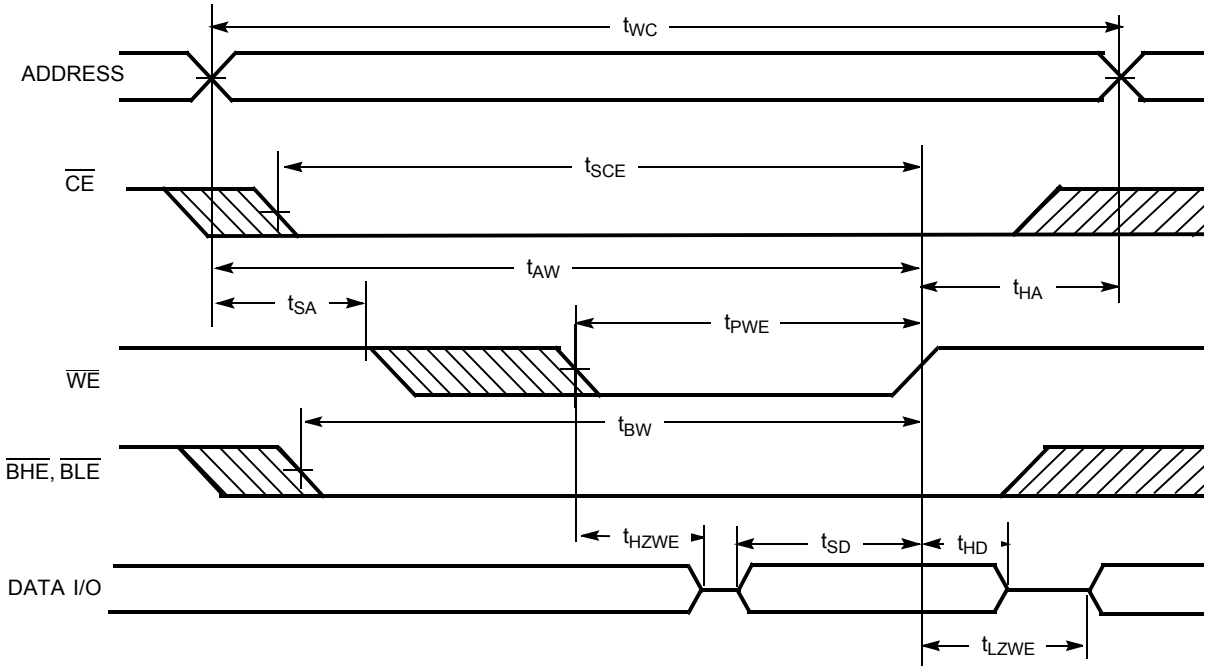
Write Cycle No. 2 ($\overline{BLE}$ or $\overline{BHE}$ Controlled)



Notes:
15. Data I/O is high impedance if $\overline{OE}$ or $\overline{BHE}$ and/or $\overline{BLE}$= V_{IH}.
16. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ going HIGH, the output remains in a high-impedance state.

Switching Waveforms (continued)

Write Cycle No. 3 ($\overline{WE}$ Controlled, LOW)



Truth Table

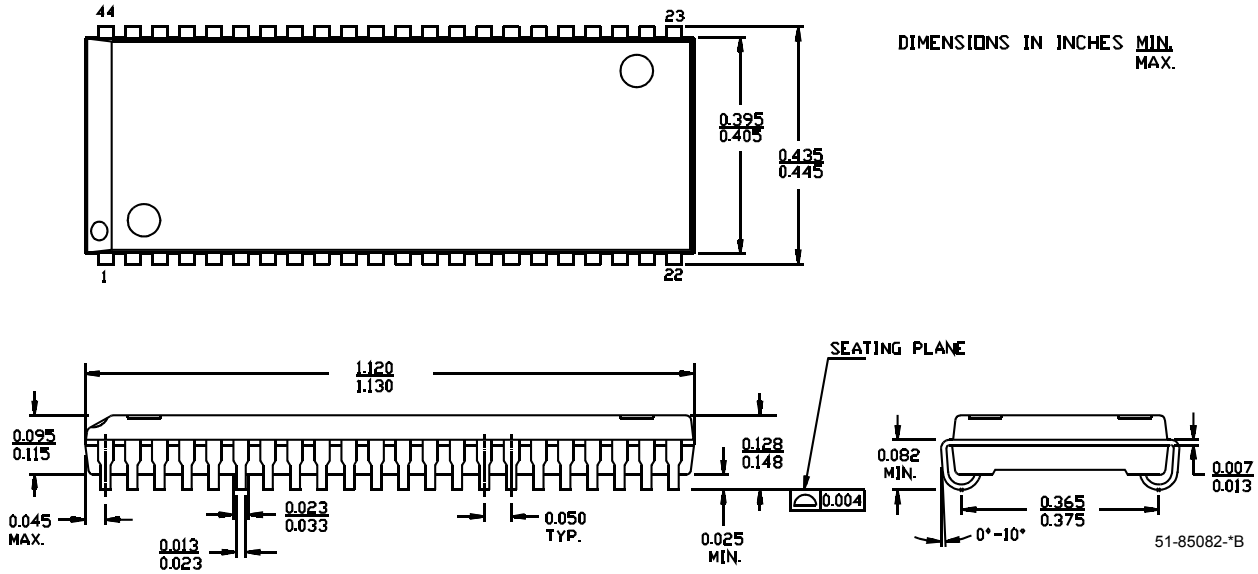
$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{BLE}$	$\overline{BHE}$	I/O_1–I/O_8	I/O_9–I/O_{16}	Mode	Power
H	X	X	X	X	High-Z	High-Z	Power-down	Standby (I_{SB})
L	L	H	L	L	Data Out	Data Out	Read – All bits	Active (I_{CC})
			L	H	Data Out	High-Z	Read – Lower bits only	Active (I_{CC})
			H	L	High-Z	Data Out	Read – Upper bits only	Active (I_{CC})
L	X	L	L	L	Data In	Data In	Write – All bits	Active (I_{CC})
			L	H	Data In	High-Z	Write – Lower bits only	Active (I_{CC})
			H	L	High-Z	Data In	Write – Upper bits only	Active (I_{CC})
L	H	H	X	X	High-Z	High-Z	Selected, Outputs Disabled	Active (I_{CC})
L	X	X	H	H	High-Z	High-Z	Selected, Outputs Disabled	Active (I_{CC})

Ordering Information

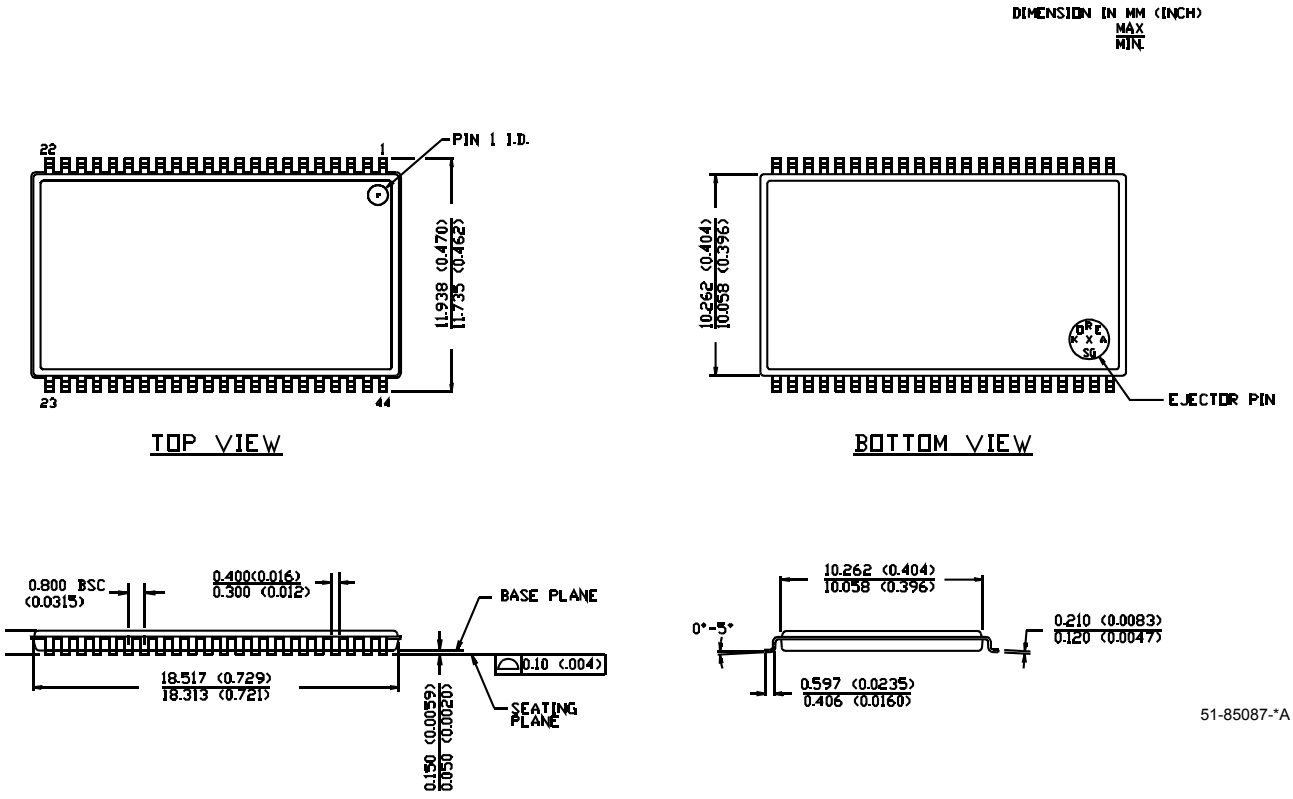
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	WCFS1016V1C-JC12	V34	44-lead (400-Mil) Molded SOJ	Commercial
	WCFS1016V1C-TC12	Z44	44-lead TSOP Type II	Commercial

Package Diagrams

44-Lead (400-Mil) Molded SOJ V34



44-pin TSOP II Z44



Document History Page

Document Title: WCFS1016V1C 64K x 16 Static RAM Document Number: 38-0xxxx				
REV.	**ECN NO.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	See ECN	4/19/02	XFL	New Data Sheet
*A	See ECN	See ECN	RKF	Added 44-pin TSOP-II Package option